ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit device includes a differential output driver circuit arranged at each I/O portion, and a delay element. The differential output driver circuit receives a pair of differential signals generated by a circuit on the input stage. An output signal from the differential output driver circuit is transmitted through the first and second signal lines. Each of the first and second signal lines includes a global interconnection, bump, and transmission line. The delay element is inserted in at least one of the first and second signal lines. The delay element delays signals passing through the signal lines so as to make the delays of the signals substantially equal to each other, compensating for the signal delay time generated by the line length difference.